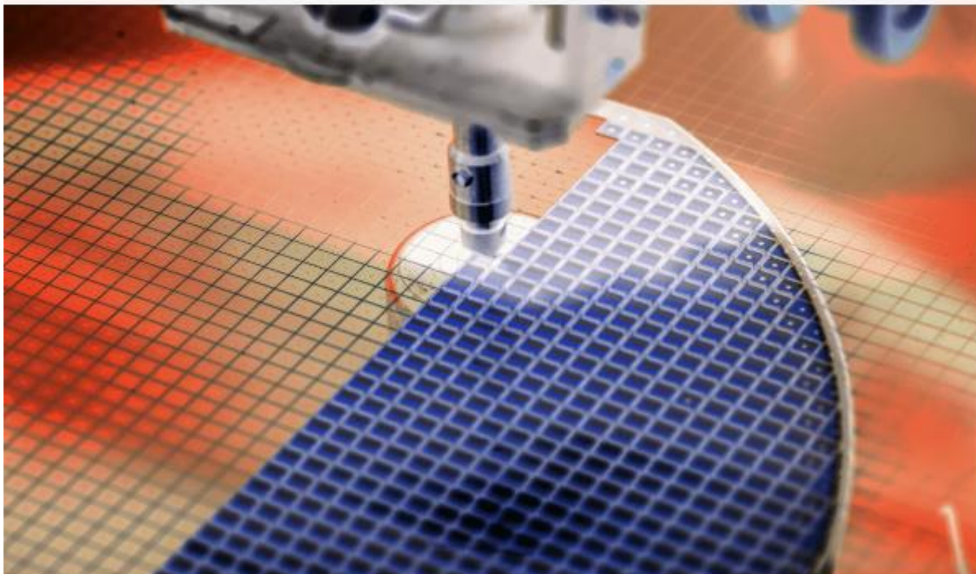
EV Group Completes Construction of New Manufacturing V Building at Corporate Headquarters to Expand Production Capacity – December 1, 2023



Flux-less TCB for Fine-Pitch Applications and Its Extension to Cu-Cu TCB

Typical interconnects are composed of solder-capped copper pillars, which exist either on a chip, on a substrate, or in some cases on both sides. The finest pitches in more recent advanced packaging applications range from 25 – 80µm and are implemented either through a conventional mass reflow (MR) or via a more sophisticated thermal compression bonding (TCB) process. The pitch and dimension scaling below 50µm, though very enticing, comes with challenges that cannot always be surmounted using traditional flux-based processes.

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Recommended Reads

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US Government Addresses Domestic Chipmaking Weaknesses with $3 Billion Advanced Packaging Program – Tom's Hardware

Events Calendar

25th IEEE Electronics Packaging Technology Conference
December 5-8, 2023

69th Annual IEEE International Electron Devices Meeting
December 9-13, 2023

SEMICON Japan 2023
December 13-15, 2023

SEMI ISS
December 7-10, 2024